



Compset MagikFoam SF250

Compset engineering

Description :

Compset SF250 is a closed-cell expanding epoxy system capable of expanding up to 4 times its mixed volume. It will adhere to surfaces such as polyester, vinyl ester and aluminium, as the foams surface is produced clean and dry, unlike other foams that sometimes need abrading to provide a mechanic key.

Compset SF250 is ideal for filling void areas of complex and hard-to-reach places, or to add volume for insulation or buoyancy. It will not absorb water and is chemically resistant to fuel and oils.

Compset SF250 is a light but extremely tough and durable core material, reaching a density of around 240kg/m³ in its freeform capacity, and has a uniform cell structure, though outside the expanded yield will be very low void content. The foam can be machined milled and sanded with conventional wood working tools to shape or finish to the final desired outcome.

The system has a cream time of approximately 20-22 minutes at 25°C after mixing, allowing for good pour time. Alternate hardeners can be used in the system to extend the mix and cream time as required. See data for reference.

Usages include ..

- centre-board & rudder construction
- strengthening of cylindrical composites
- lightweight tooling composite backups
- thermal insulation
- "in-situ" core bonding and gap filling
- core replacement of complex shapes
- buoyancy
- pressure resistant underwater composites

Hardener Grade	Working time 25°C 1 litre
Slow	60 minutes
X-Slow	100 minutes
Fast	25 minutes

application:

Part A Compset SF250 resin (White thixotropic gel) mixing 5 Parts A by weight
 Part B SF250 Hardener (clear liquid) to 1 Part B by weight

Pour density 1100 g/L unexpanded
 Final density 250 - 300 g/L expanded (depending on pour geometry)
 Expansion Factor x 3.5 to x 4.5

Recommended pour size 20°C 2.5L X-Slow hardener ~ 10L expanded
 Demoulding time 24 hrs 20°C

engineering:

Mechanical Properties

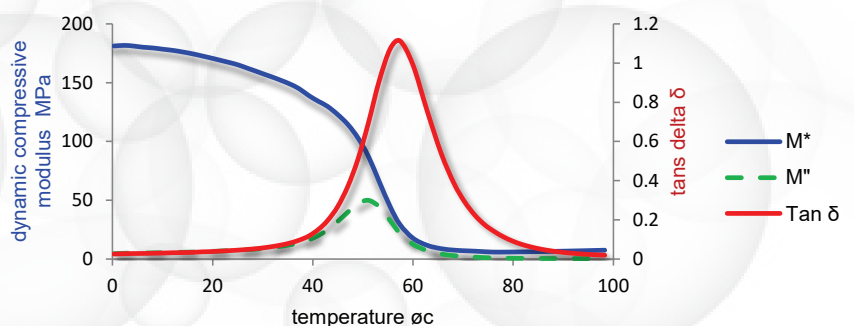
static

	24H/40°C	16H/80°C
Compressive Strength Mpa	11.2	14.2
Compressive Modulus MPa	1200	1250
Yield %	9.40	

Dynamic

Tg DSC Midpoint	58°C	86°C
Onset	57°C	76°C
ultimate	71°C	95°C

Compressive modulus	180 MPa
tan alpha	51°C
tan delta	57°C



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